Title (en)
LEADFRAME INTERPOSER

Title (de)
LEADFRAME INTERPOSER

Title (fr)
INTERPOSEUR DE GRILLE DE CONNEXION

Publication
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Application
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Abstract (en)
[origin: WO0159840A1] The invention relates to a leadframe interposer provided with an upset which is formed by an elevated section in a middle area, and the vertical dimensions of the interposer are enlarged there so that when assembling a housing stack consisting of a number of semiconductor chips, the elevated section presses against an upper side or lower side of a chip housing thereby exerting a compensating turning moment onto the interposer which prevents a possible twisting or deformation from occurring when applying the connecting conductors to the laterally offset contact regions of the interposer.

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